

# RK7002A

- 1) Low on-resistance.
- 2) High ESD
- 3) High-speed switching.
- 4) Low-voltage drive (4V).
- 5) Easily designed drive circuits.
- 6) Easy to use in parallel.

Silicon N-channel  
MOSFET transistor

Gate Protection Diode.

\* A protection diode has been built in between the gate and the source to protect against static electricity when the product is in use.  
Use the protection circuit when fixed voltages are exceeded.

The drawing shows the SST3 package in two views. The top view is a square package with a central square area. Dimensions include a total width of 2.4, a central square width of 1.3, and a distance of 0.4 from the top edge to the center. The central square has a width of 0.95 and a height of 1.9. There are four pins, labeled (1), (2), (3), and (4), with dimensions 0.95, 0.95, 0.95, and 0.95 respectively. The side view shows a package with a height of 0.15, a top width of 0.45, and a bottom width of 0.1. The distance from the bottom edge to the center of the package is 0.2 Min. Each lead has the same dimensions.

ROHM : SST3  
EIAJ : SOT-23

Abbreviated symbol : RKS

(1) Source  
(2) Gate  
(3) Drain

| Parameter               |            | Symbol         | Limits          | Unit               |
|-------------------------|------------|----------------|-----------------|--------------------|
| Drain-source voltage    |            | $V_{DSS}$      | 60              | V                  |
| Gate-source voltage     |            | $V_{GSS}$      | $\pm 20$        | V                  |
| Drain current           | Continuous | $I_D$          | 300             | mA                 |
|                         | Pulsed     | $I_{DP}^{*1}$  | 1.2             | A                  |
| Drain reverse current   | Continuous | $I_{DR}$       | 300             | mA                 |
|                         | Pulsed     | $I_{DRP}^{*1}$ | 1.2             | A                  |
| Total power dissipation |            | $P_D^{*2}$     | 200             | mW                 |
| Channel temperature     |            | $T_{ch}$       | 150             | $^{\circ}\text{C}$ |
| Storage temperature     |            | $T_{stg}$      | $-55 \sim +150$ | $^{\circ}\text{C}$ |

\*1  $P_w \leq 10\mu s$ , Duty cycle  $\leq 1\%$

\*2 When using 1×0.75×0.062 inch glass epoxy board.

## Transistors

## ●Electrical characteristics (Ta=25°C)

| Parameter                        | Symbol            | Min. | Typ. | Max.     | Unit     | Test Conditions                             |
|----------------------------------|-------------------|------|------|----------|----------|---------------------------------------------|
| Gate leakage current             | $I_{GSS}$         | —    | —    | $\pm 10$ | $\mu A$  | $V_{GS}=\pm 20V$ , $V_{DS}=0V$              |
| Drain-source breakdown voltage   | $V_{(BR)DSS}$     | 60   | —    | —        | V        | $I_D=10\mu A$ , $V_{GS}=0V$                 |
| Drain cutoff current             | $I_{DSS}$         | —    | —    | 1        | $\mu A$  | $V_{DS}=60V$ , $V_{GS}=0V$                  |
| Gate threshold voltage           | $V_{GS(th)}$      | 1    | —    | 2.5      | V        | $V_{DS}=10V$ , $I_D=1mA$                    |
| Drain-source on-state resistance | $R_{DS(on)}^{*1}$ | —    | 0.7  | 1.0      | $\Omega$ | $I_D=300mA$ , $V_{GS}=10V$                  |
|                                  |                   | —    | 1.1  | 1.5      |          | $I_D=300mA$ , $V_{GS}=4V$                   |
| Forward transfer admittance      | $ Y_{fs} ^{*1}$   | 200  | —    | —        | mS       | $V_{DS}=10V$ , $I_D=300mA$                  |
| Input capacitance                | $C_{iss}$         | —    | 33   | —        | pF       | $V_{DS}=10V$<br>$V_{GS}=0V$<br>$f=1MHz$     |
| Output capacitance               | $C_{oss}$         | —    | 14   | —        | pF       |                                             |
| Reverse transfer capacitance     | $C_{rss}$         | —    | 9    | —        | pF       |                                             |
| Turn-on delay time               | $t_{d(on)}^{*2}$  | —    | 6    | —        | ns       | $I_D=150mA$ , $V_{DD}=30V$<br>$V_{GS}=10V$  |
| Rise time                        | $t_r^{*2}$        | —    | 5    | —        | ns       |                                             |
| Turn-off delay time              | $t_{d(off)}^{*2}$ | —    | 13   | —        | ns       | $R_L=200\Omega$<br>$R_{GS}=10\Omega$        |
| Fall time                        | $t_f^{*2}$        | —    | 80   | —        | ns       |                                             |
| Total gate charge                | $Q_g^{*2}$        | —    | 3    | 6        | nC       | $V_{DD}=30V$<br>$V_{GS}=10V$<br>$I_D=200mA$ |
| Gate-source charge               | $Q_{gs}^{*2}$     | —    | 0.6  | —        | nC       |                                             |
| Gate-drain charge                | $Q_{gd}^{*2}$     | —    | 0.5  | —        | nC       |                                             |

\*1  $P_W \leq 300\mu s$ , Duty cycle  $\leq 1\%$ 

\*2 Pulsed

## ●Packaging specifications

|         |                              |        |
|---------|------------------------------|--------|
| Type    | Package                      | Taping |
|         | Code                         | T116   |
|         | Basic ordering unit (pieces) | 3000   |
| RK7002A |                              | ○      |

## ●Electrical characteristic curves

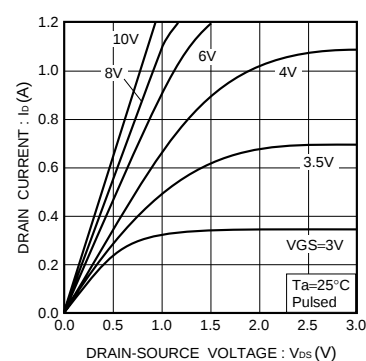


Fig.1 Typical output characteristics

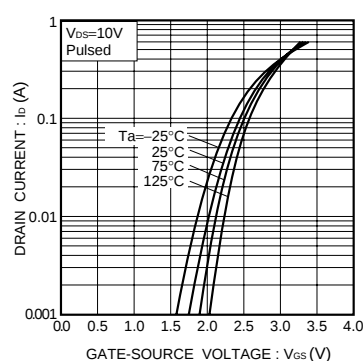
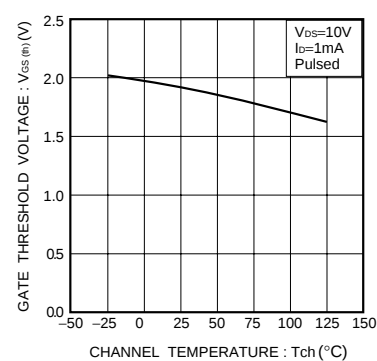


Fig.2 Typical transfer characteristics

Fig.3 Gate threshold voltage  
vs. channel temperature

## Transistors

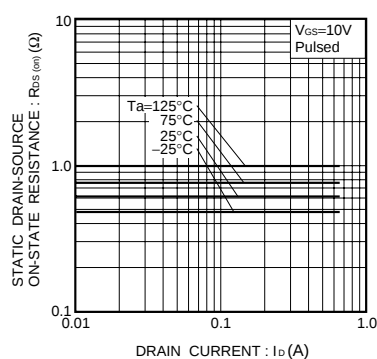


Fig.4 Static drain-source on-state resistance vs. drain current ( I )

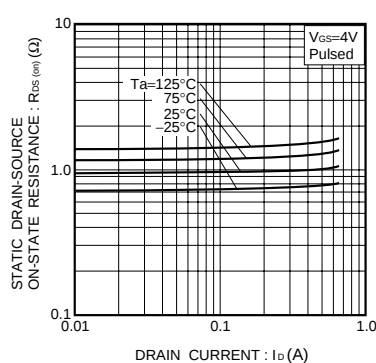


Fig.5 Static drain-source on-state resistance vs. drain current ( II )

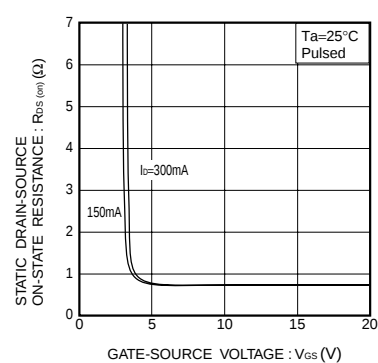


Fig.6 Static drain-source on-state resistance vs. gate-source voltage

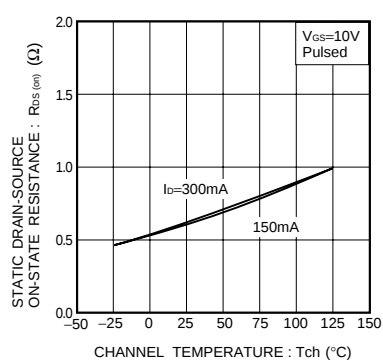


Fig.7 Static drain-source on-state resistance vs. channel temperature

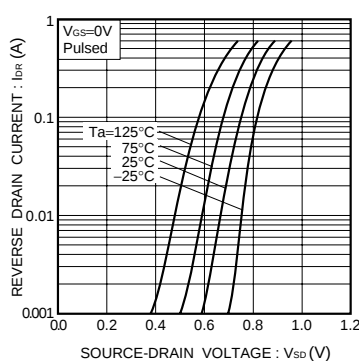


Fig.8 Reverse drain current vs. source-drain voltage ( I )

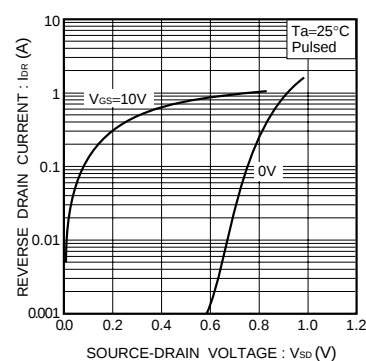


Fig.9 Reverse drain current vs. source-drain voltage ( II )

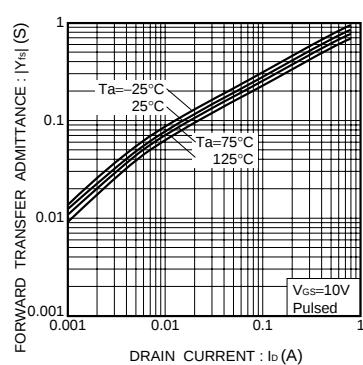


Fig.10 Forward transfer admittance vs. drain current

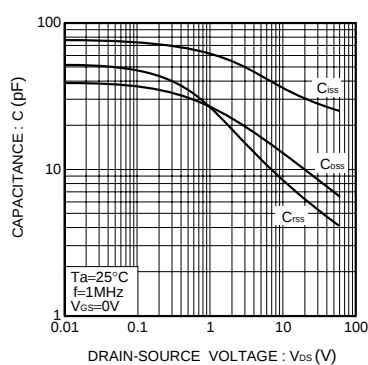
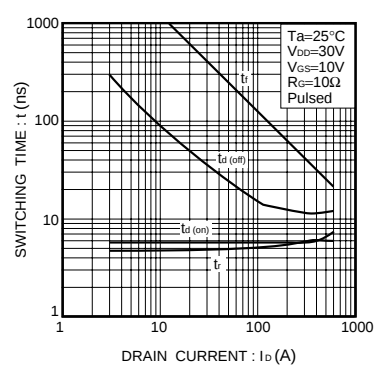


Fig.11 Typical capacitance vs. drain-source voltage

Fig.12 Switching characteristics  
(See Figures 13 and 14 for the measurement circuit and resultant waveforms)

## Transistors

### ● Switching characteristics measurement circuit

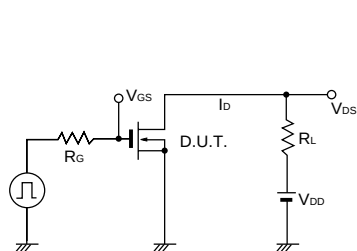


Fig.13 Switching time measurement circuit

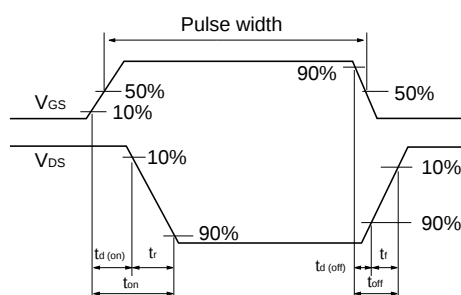


Fig.14 Switching time waveforms